



HJ32C

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HJ32C is designed for use in general purpose amplifier and low speed switching applications.

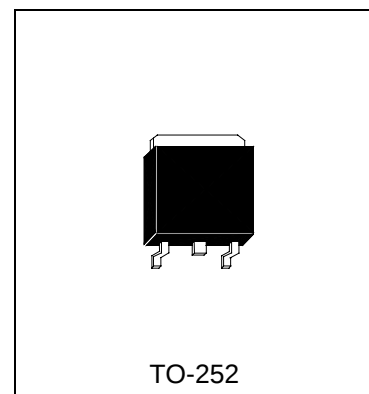
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 15 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage -100 V
BVCEO Collector to Emitter Voltage -100 V
BVEBO Emitter to Base Voltage -5 V
IC Collector Current -3 A

Characteristics (Ta=25°C)

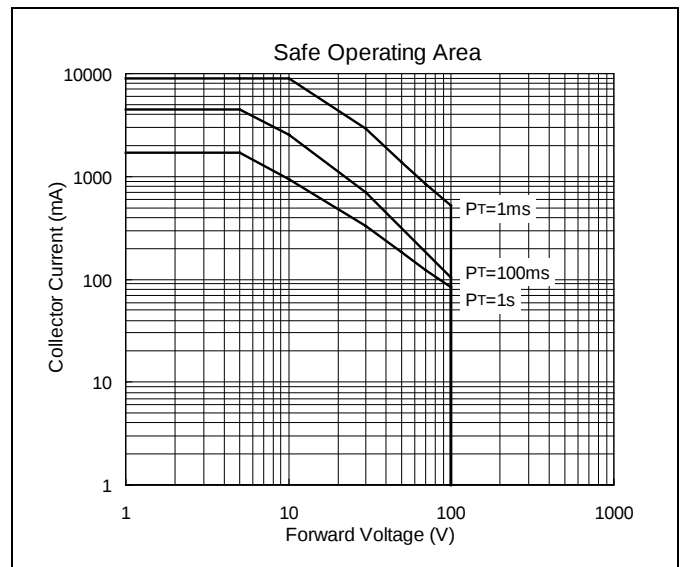
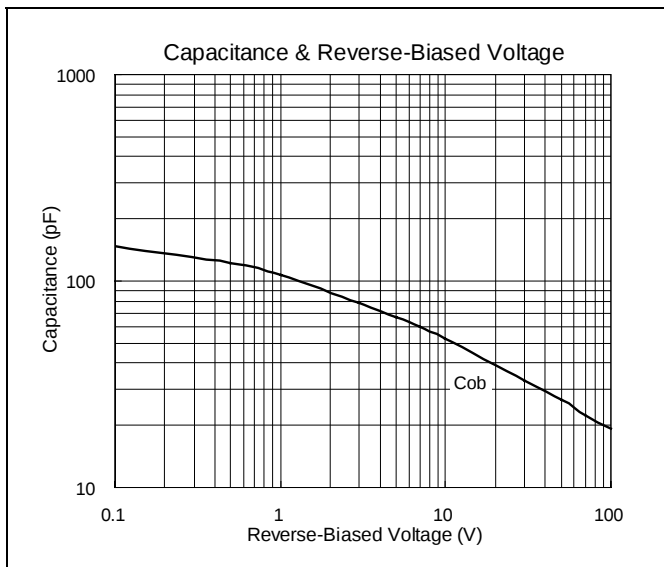
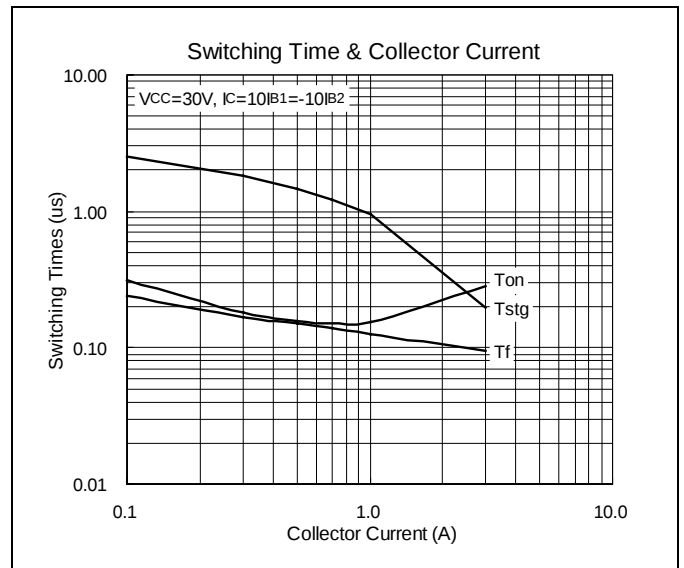
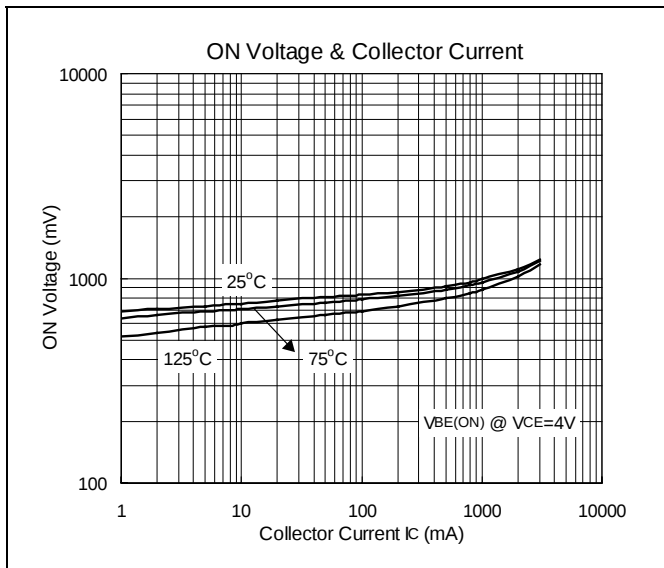
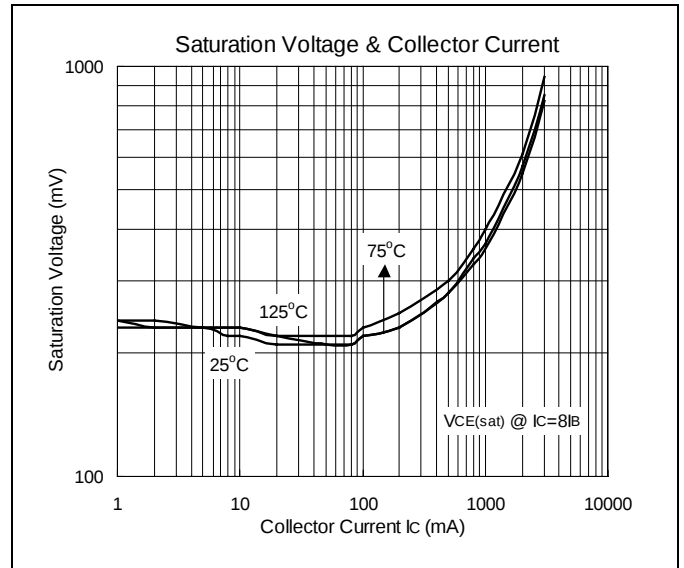
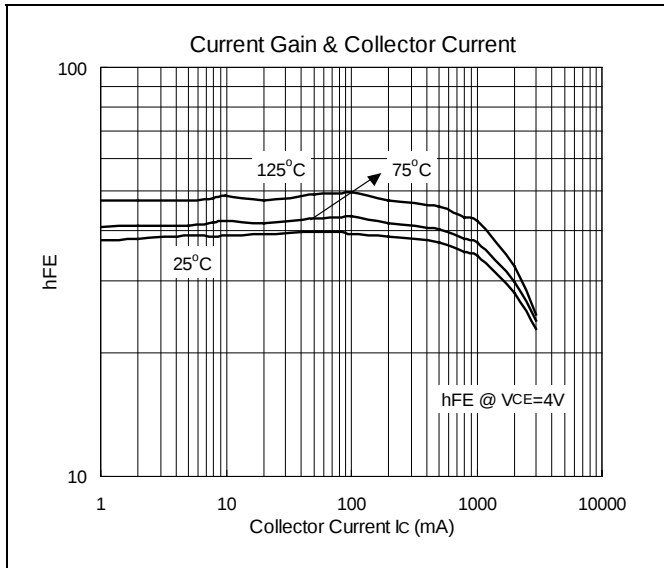
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-100	-	-	V	IC=-1mA, IE=0
BVCEO	-100	-	-	V	IC=-30mA, IB=0
ICES	-	-	-20	uA	VCE=-100V, VEB=0
ICEO	-	-	-50	uA	VCE=-60V, IB=0
IEBO	-	-	-1	mA	VEB=-5V, IC=0
*VCE(sat)	-	-	-1.2	V	IC=-3A, IB=-375mA
*VBE(on)	-	-	-1.8	V	VCE=-4V, IC=-3A
*hFE1	25	-	-		VCE=-4V, IC=-1A
*hFE2	10	-	50		VCE=-4V, IC=-3A
fT	3	-	-	MHz	VCE=-10V, IC=-500mA, f=1MHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



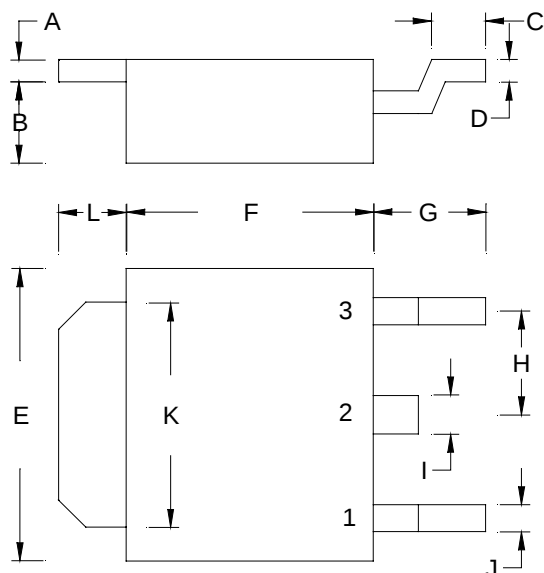


Characteristics Curve



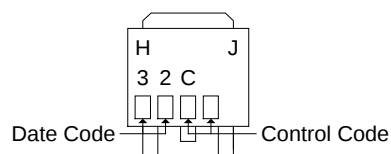


TO-252 Dimension



3-Lead TO-252 Plastic Surface Mount Package
HSMC Package Code: J

Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes: 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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